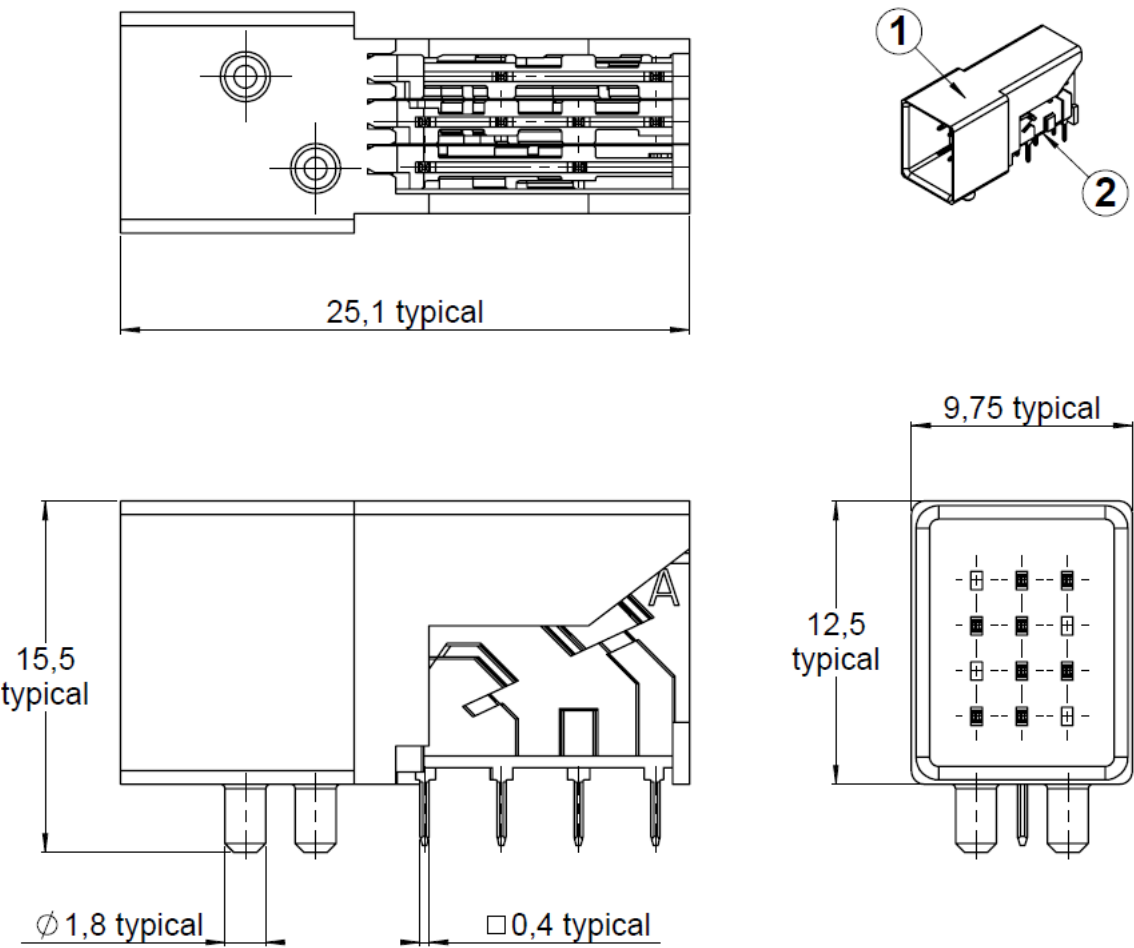


PAGE 1/6	ISSUE 14-02-19A	SERIES OCTIS	PART NUMBER OCTI460500
----------	-----------------	--------------	------------------------



All dimensions are in mm. Tolerances according ISO 2768 m-H

DESCRIPTION

REP	COMPONENT	MATERIALS	PLATING
1	Housing	PLASTIC	-
2	Contact	COPPER ALLOY	SN

PAGE 2/6

ISSUE 14-02-19A

SERIES OCTIS

PART NUMBER OCTI460500

GENERAL CHARACTERISTICS

Mechanical Mating endurance (cycles) Vibration Weight (g)	IEC 61300-2-2 EIA 364-28 -	100 - 1.3440
Environmental Operating temperature (°C) Storage temperature (°C) RoHS Flammability	IEC 61300-2-22 IEC 61300-2-22 - UL 94	-40 / +85 -65 / +85 Compliant V0
Electrical Working voltage (V AC Max) Contact resistance (mΩ max) Current rating (A) Insulation resistance (MΩ min)	- EIA 364-23B EIA 364-70A EIA 364-21C	300 55 1 A per contact (all contacts powered) 5000 (after environmental exposure)
Signal Integrity performance Cross talk Impedance of pairs IL RL	- - - -	Pair to pair @20MHz < -60dB All pairs to one victim @ 20MHz < -54dB (powersum) 100Ω +/- 10% @ 30 MHz < 0.1 dB @ 30MHz < -37 dB @ 20MHz
Others Packaging	-	Packaging in Tape&Reel (Quantity per reel to be defined)

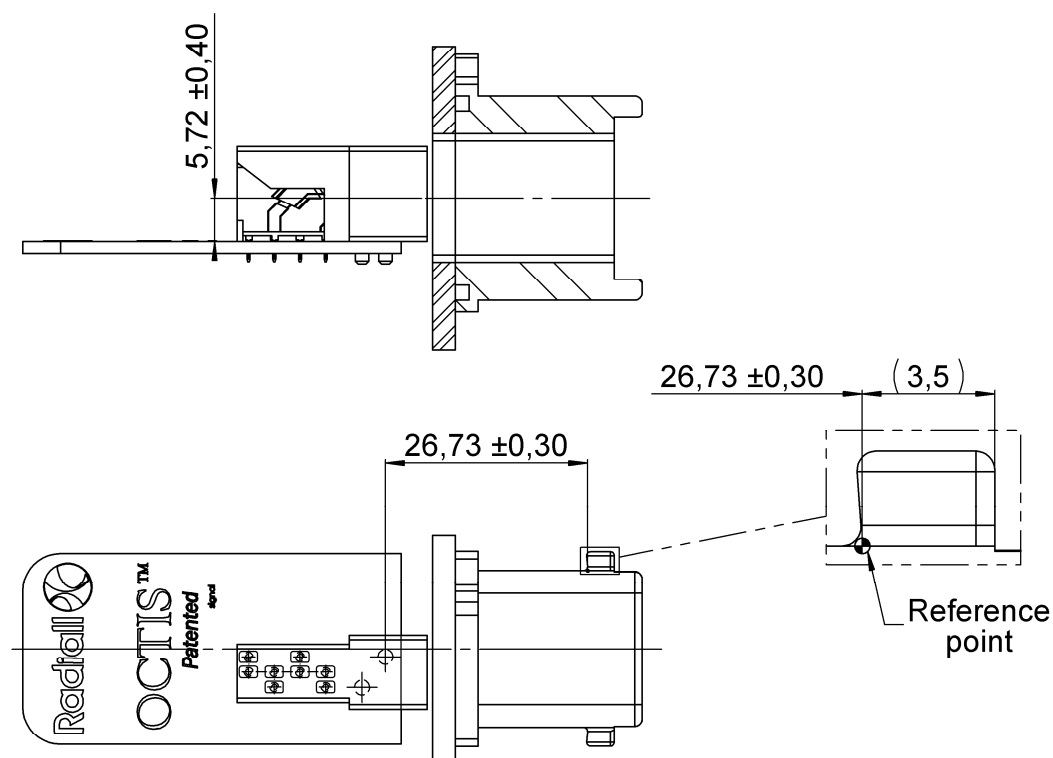
PAGE 3/6

ISSUE 14-02-19A

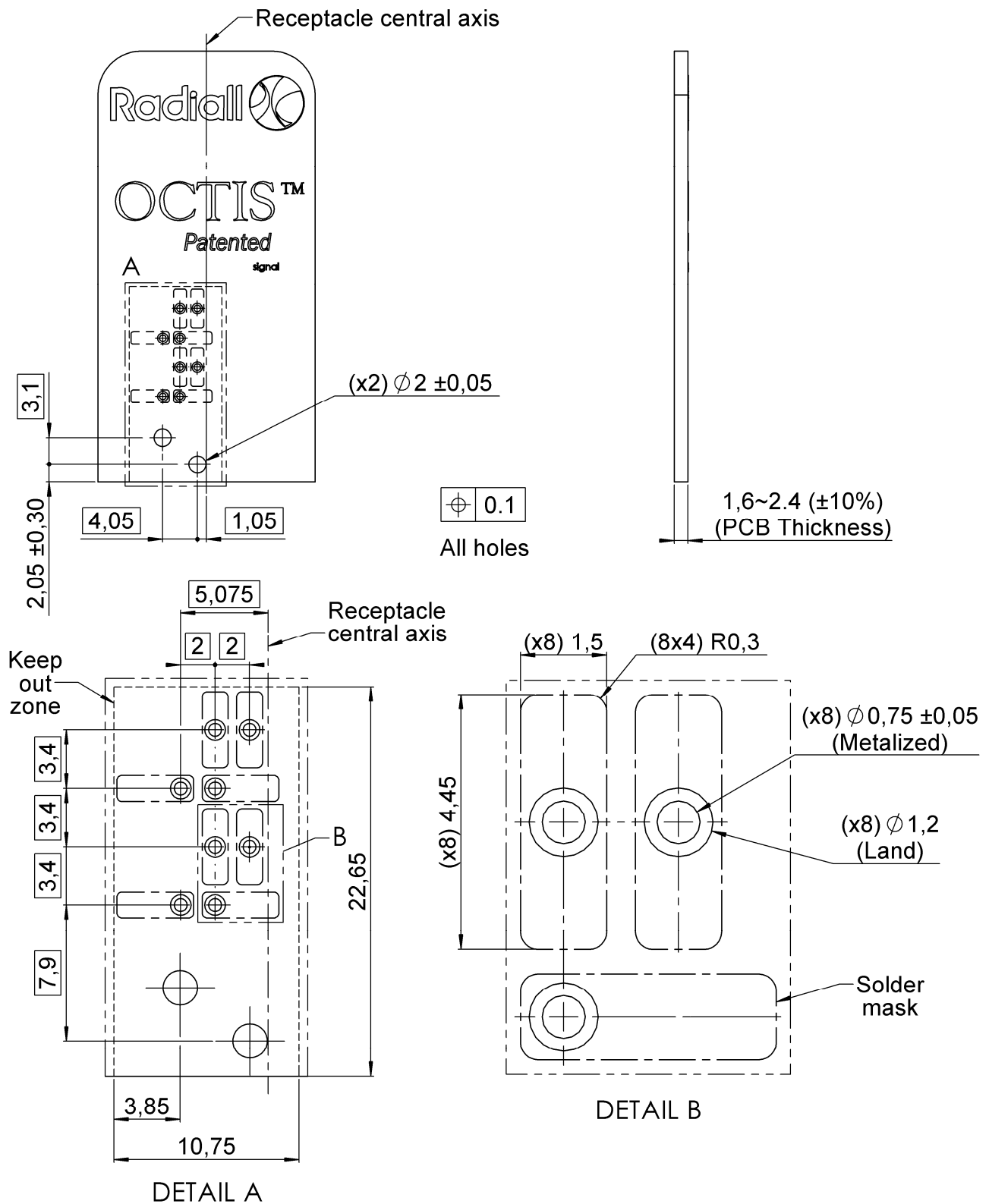
SERIES OCTIS

PART NUMBER OCTI460500

POSITIONING AND PATTERN DEFINITION



FOOT/PRINT (General tolerance for PCB ± 0.1 mm)



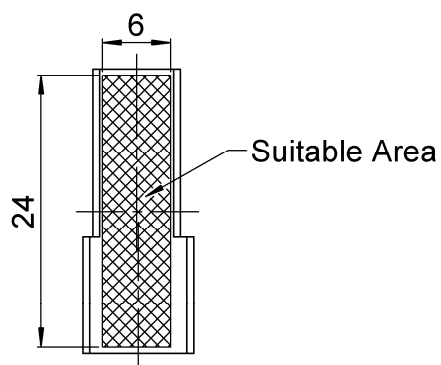
PAGE 5/6

ISSUE 14-02-19A

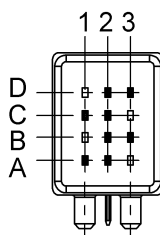
SERIES OCTIS

PART NUMBER OCTI460500

SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



CONTACTS CONFIGURATION



PAGE 6/6

ISSUE 14-02-19A

SERIES OCTIS

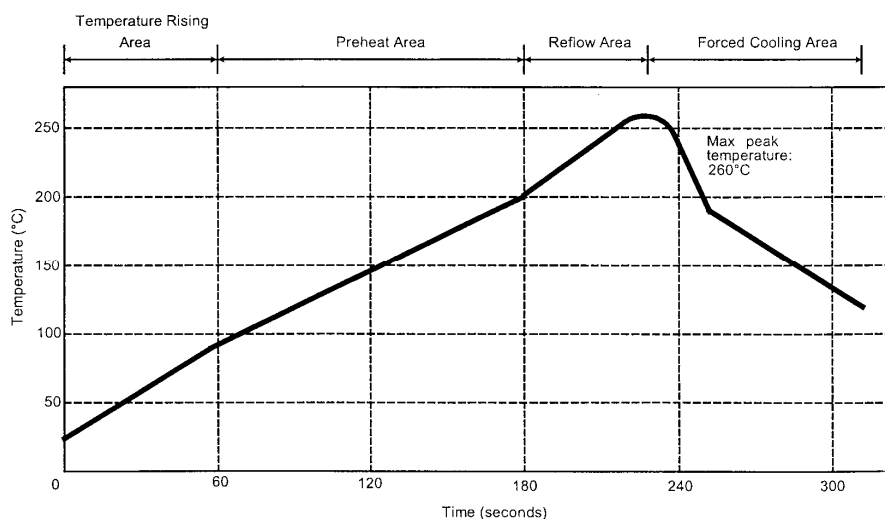
PART NUMBER OCTI460500

SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine.
A video camera is recommended for a good positioning of the component.
Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven.
Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

* Typical data for reflow process. Alternatively, wave soldering is also possible